

N-Channel Super Junction Power MOSFET $\, \mathrm{I\!V} \,$

General Description

The series of devices use advanced trench gate super junction technology and design to provide ultra-low RDS(ON) and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

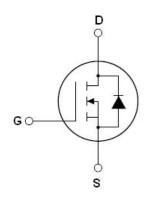
F	Δ	a	tı	11	'e	c
	C	a	u	41	C	3

- New technology for high voltage device
- Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- High reliability
- ROHS compliant

Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger(OBC)

V _{DS min@Tjmax}	710	V
R _{DS(ON)TYP}	85	mΩ
ID	36	Α
Qg	55	nC



Schematic diagram

♦ Intrinsic fast-recovery body diode

Package Marking And Ordering Information

Device	Device Package	Marking	
NCE65NF099D	TO-263	NCE65NF099D	



TO-263

V1.1

Table 1. Absolute Maximum Ratings (T_c=25℃)

Parameter	Symbol	Value	Unit
Drain-Source Voltage (Vgs=0V)	VDS	650	V
Gate-Source Voltage (V _{DS} =0V) AC (f>1 Hz)	V _G S	±30	V
Gate-Source Voltage (V _{DS} =0V) DC	V _G S	±20	V
Continuous Drain Current at Tc=25°C	I _{D (DC)}	36	А
Continuous Drain Current at Tc=100°C	I _{D (DC)}	25.2	А
Pulsed drain current (Note 1)	I _{DM (pluse)}	108	Α
Maximum Power Dissipation(Tc=25℃)	P _D	346	W
Derate above 25°C		2.30	W/°C
Single pulse avalanche energy (Note 2)	Eas	324	mJ
Avalanche current ^(Note 1)	I _{AS}	9	Α
Repetitive Avalanche energy , t_{AR} limited by T_{jmax} (Note 1)	E _{AR}	3.9	mJ



Parameter	Symbol	Value	Unit
Drain Source voltage slope, V _{DS} ≤480 V,	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS} \leq 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range	T_{J},T_{STG}	-55+175	°C

^{*} limited by maximum junction temperature

Table 2. Thermal Characteristic

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R _{thJC}	0.43	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R _{thJA}	62	°C /W

Table 3. Electrical Characteristics (TA=25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states	1	·				
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =1mA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I _{DSS}	V _{DS} =650V,V _{GS} =0V			400	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =500uA	3	4	5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =18A		85	99	mΩ
Dynamic Characteristics						
Input Capacitance	C _{lss}	.,		2800	3200	pF
Output Capacitance	Coss	V _{DS} =50V,V _{GS} =0V,		96		pF
Reverse Transfer Capacitance	Crss	F=1.0MHz		6		pF
Total Gate Charge	Qg			55	60	nC
Gate-Source Charge	Q _{gs}	V _{DS} =480V,I _D =18A,		16.5		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		25.5		nC
Gate plateau voltage	Vgp			7.3		V
Intrinsic gate resistance	R _G f = 1 MHz open drain			1.5		Ω
Switching times						
Turn-on Delay Time	t _{d(on)}			15		nS
Turn-on Rise Time	t _r	V_{DD} =380 V , I_{D} =18 A ,		14		nS
Turn-Off Delay Time	t _{d(off)}	$R_G=1.7\Omega, V_{GS}=10V$		72		nS
Turn-Off Fall Time	t _f			14		nS
Source- Drain Diode Characteristics	•					
Source-drain current(Body Diode)	I _{SD}	T 0500			36	Α
Pulsed Source-drain current(Body Diode)	I _{SDM}	- T _C =25°C			108	Α
Forward On Voltage	V _{SD}	Tj=25°C,I _{SD} =36A,V _{GS} =0V		1.0	1.2	V
Reverse Recovery Time	t _{rr}			160		nS
Reverse Recovery Charge	Qrr	Tj=25°C,I _F =18A,di/dt=100A/μs		0.96		uC
Peak Reverse Recovery Current	I _{rrm}	1		12		Α

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

^{2.} Tj=25 $^{\circ}$ C,VDD=50V,VG=10V, R_G=25 Ω



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure 1. Safe operating area

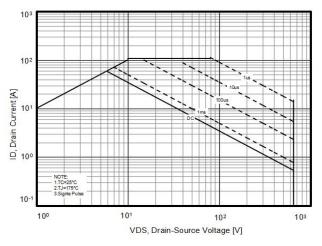


Figure 3. Output characteristics

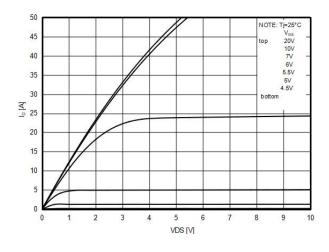


Figure 5. Static drain-source on resistance

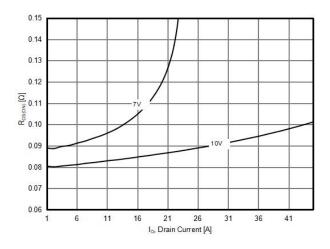


Figure 2. Capacitance

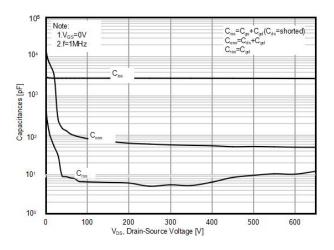


Figure 4. Source-Drain Diode Forward Voltage

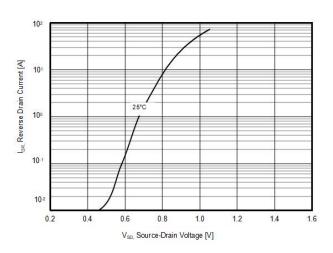


Figure 6. Transfer characteristics

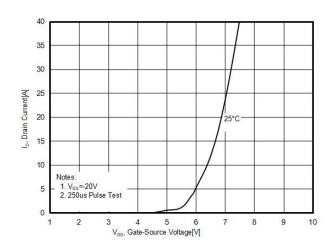




Figure 7. R_{DS(ON)} vs Junction Temperature

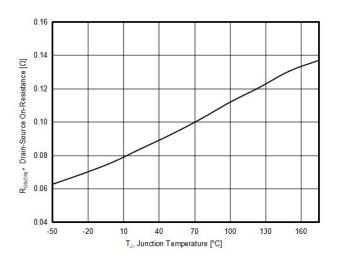


Figure 8. BV_{DSS} vs Junction Temperature

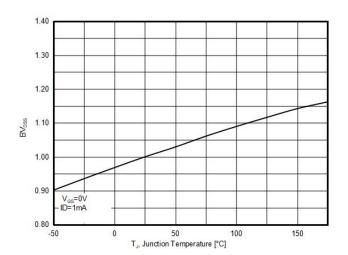


Figure 9. Gate charge waveforms

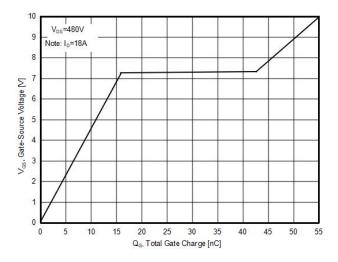
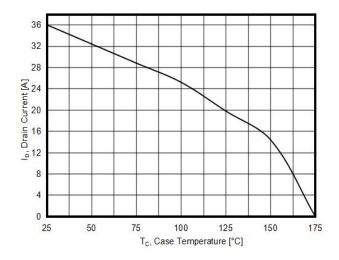


Figure 10. Maximum I_D vs Junction Temperature

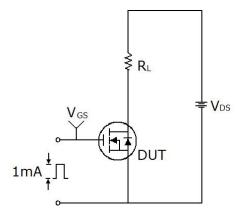


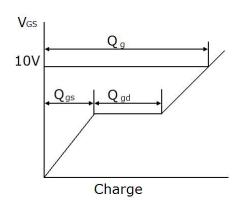
V1.1



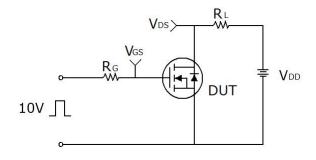
Test circuit

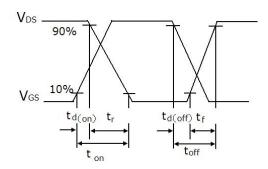
1) Gate charge test circuit & Waveform



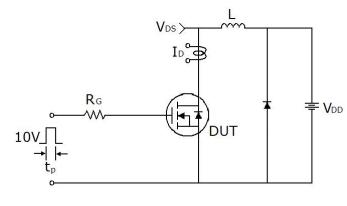


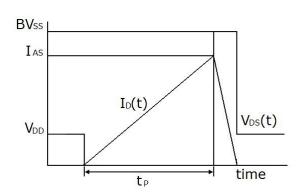
2) Switch Time Test Circuit:





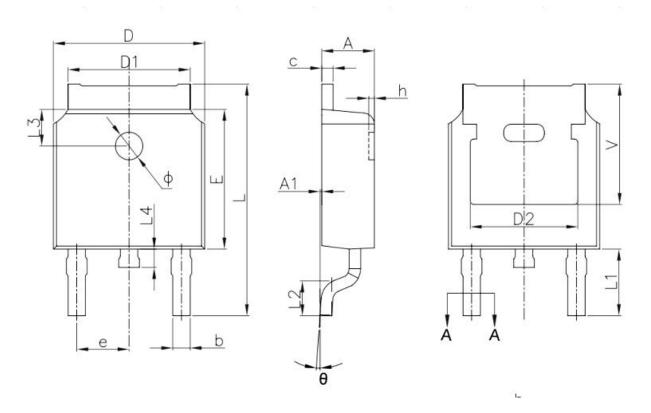
3) Unclamped Inductive Switching Test Circuit & Waveforms







TO-263 (E) Package Information



Symbol	Dimensions In Millimeters		Dimensions	In Inches		
	Min.	Max.	Min.	Max.		
A	4.20	4.60	0.165	0.181		
A1	-	0.25	-	0.010		
A2	2.20	2.60	0.087	0.102		
b	0.70	0.90	0.028	0.035		
b2	1.17	1.37	0.046	0.054		
С	0.40	0.60	0.016	0.024		
c1	1.15	1.40	0.045	0.055		
D	9.10	9.30	0.358	0.366		
D1	7.63	8.23	0.300	0.324		
E	10.05	10.45	0.396	0.411		
E1	8.35	8.95	0.329	0.352		
е	2.54	BSC	0.100 BSC			
Н	14.61	15.88	0.575	0.625		
L	1.78	2.79	0.070	0.110		
L1	1.36REF		0.053REF			
L2	1.3F	1.3REF		0.051REF		
L3	0.25	0.25REF		REF		



ATTENTION:

- Any and all NCE products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your NCE representative nearest you before using any NCE products described or contained herein in such applications.
- NCE assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all NCE products described or contained herein.
- Specifications of any and all NCE products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- NCE Power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all NCE products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of NCE Power Semiconductor CO.,LTD.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. NCE believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the NCE product that you intend to use.
- This catalog provides information as of Mar. 2010. Specifications and information herein are subject to change without notice.